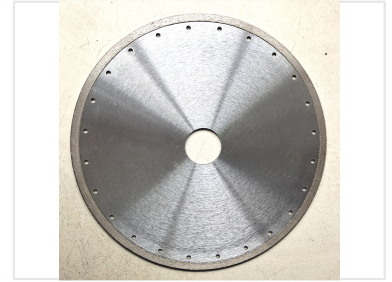


Diamond Cutting Blade for Electroceramics

This diamond cutting blade is designed for cutting electroceramics and electric porcelain. It delivers clean and efficient cuts with minimal material loss.



ADDITIONAL IMAGES



Product Overview

Precision Diamond Cutting Solution

This high-performance diamond cutting blade is specifically engineered for the demanding requirements of electroceramics and electric porcelain processing. Utilizing advanced sintering technology, it delivers fast, stable cutting with high efficiency and minimal material loss. Designed for both wet and dry applications, it offers an extended lifespan and consistent performance for professional industrial use.

Technical Specifications

Compatible Machinery

- Tile saw
- Bevel-tile saw
- Angle grinder
- Circular saw

Size Specifications

Parameter	Value
Diameter Range	4 inch to 32 inch
Specific Size Shown	400 x 10 x 60 mm

Cutting Applications

Electroceramics, Electric Porcelain, Dry Cutting, Wet Cutting

Quality & Performance

Key Performance Metrics

100 %

QC Pass Rate

Certifications

MPA • SGS

Manufacturing Technology

Cold Press Sintered, Hot Press, Silent Core Segment

Logistics & Service

Packaging Options

- Blister packages (<230mm)
- Skin packages (<150mm)
- White box
- Brown envelope

Lead Time

3 days (in stock) / 7-15 days (out of stock)